

**ABSTRACT OF THE DISCLOSURE****APPARATUS FOR FUNCTIONAL AND STRESS TESTING OF EXPOSED  
CHIP LAND GRID ARRAY DEVICES**

A chip testing system with improved thermal performance. In a preferred embodiment, a nest assembly of a chip testing apparatus includes tooling balls and a fitted frame for improving alignment of a coldplate and a chip surface. In preferred embodiments, the coldplate is of unibody design. Thermal performance is also improved by balancing the forces exerted on the coldplate using an adjustable hose mounting bracket. The bracket allows the forces exerted by the hoses on the coldplate to be adjusted so they balance and cancel other unwanted forces on the cold plate.